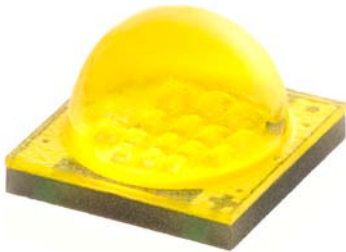


# Cree® XLamp® XM-L HVW LEDs



## PRODUCT DESCRIPTION

The Cree XLamp XM-L High Voltage White LED provides the lighting-class performance and reliability of Cree XLamp LEDs in the standard XM package. The XM-L HVW LED is an order of magnitude smaller than other high-voltage LED arrays, allowing easy implementation of space-constrained lighting applications with smaller, more efficient high-voltage drivers. Among these applications are small lamps such as B10, GU10 and E17.

## FEATURES

- Binned at 85 °C
- Typical forward voltage of 46 V @ 44 mA, with Vf binning available
- Cree-standard XM mechanical footprint, with electrically neutral thermal path
- Low thermal resistance: 3.5 °C/W
- Wide viewing angle: 115°
- Maximum drive current: 125 mA
- Maximum junction temperature: 150 °C
- Unlimited floor life at ≤ 30 °C/85% RH
- Reflow solderable
- Available in standard CRI and 80 minimum CRI configurations

## TABLE OF CONTENTS

Flux Characteristics.....	2
Characteristics .....	2
Relative Spectral Power Distribution.....	3
Relative Flux vs. Junction Temperature .....	3
Electrical Characteristics.....	4
Thermal Design.....	4
Relative Flux vs. Current .....	5
Typical Spatial Distribution.....	5
Reflow Soldering Characteristics ..	6
Mechanical Dimensions.....	7
Tape and Reel .....	8
Packaging.....	9

## FLUX CHARACTERISTICS (T<sub>j</sub> = 85 °C)

The following table provides several base order codes for XLamp XM-L LEDs. It is important to note that the base order codes listed here are a subset of the total available order codes for the product family. For more order codes, as well as a complete description of the order-code nomenclature, please consult the XLamp XM-L Binning and Labeling document.

Color	CCT Range		Base Order Codes Min Luminous Flux @ 44 mA (lm)		Order Code
	Min.	Max.	Group	Flux (lm)	
Cool White	5,000 K	8,300 K	T3	220	XMLHVW-Q0-0000-0000LT351
			T4	240	XMLHVW-Q0-0000-0000LT451
Neutral White	3,700 K	5,000 K	S6	182	XMLHVW-Q0-0000-0000LS6E5
			T2	200	XMLHVW-Q0-0000-0000LT2E5
Warm White	2,600 K	3,700 K	S4	164	XMLHVW-Q0-0000-0000LS4E7
			S5	172	XMLHVW-Q0-0000-0000LS5E7

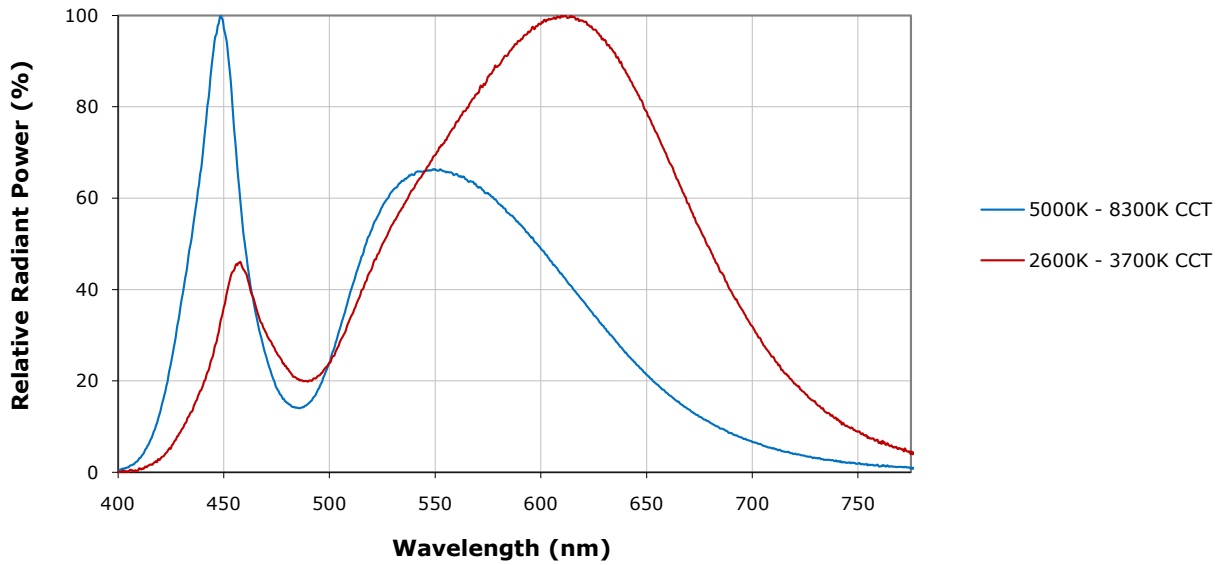
### Notes:

- Cree maintains a tolerance of  $\pm 7\%$  on flux and power measurements and  $\pm 2$  on CRI measurements.
- Typical CRI for Cool White (5,000 K – 8,300 K CCT) is 68.
- Typical CRI for Neutral White (3,700 K – 5,000 K CCT) is 75.
- Typical CRI for Warm White (2,600 K – 3,700 K CCT) is 82.

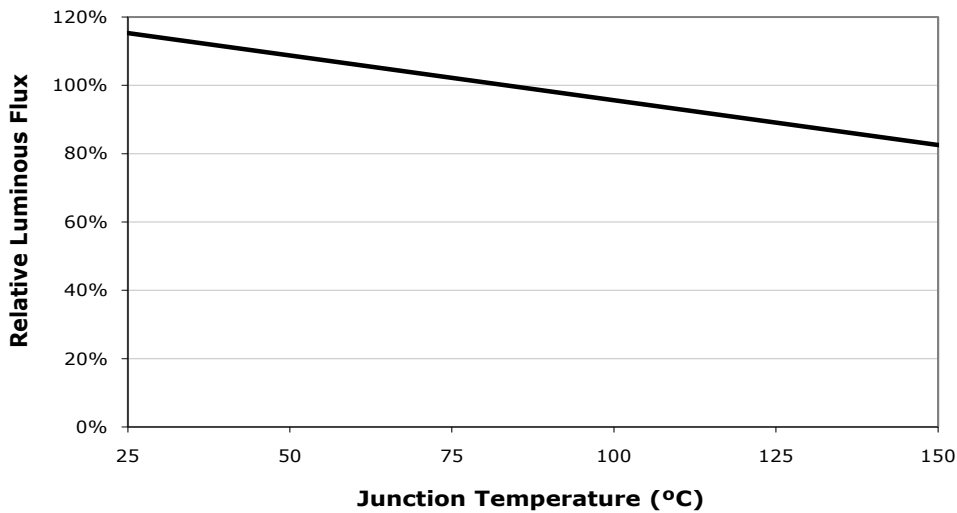
## CHARACTERISTICS

Characteristics	Unit	Minimum	Typical	Maximum
Thermal Resistance, junction to solder point	°C/W		3.5	
Viewing Angle (FWHM)	degrees		115	
Temperature coefficient of voltage	mV/°C		-35	
ESD Classification (HBM per Mil-Std-883D)			Class 2	
DC Forward Current	mA			125
Reverse Current	mA			0.1
Forward voltage (@ 44 mA, 85 °C)	V		46	55
LED Junction Temperature	°C			150

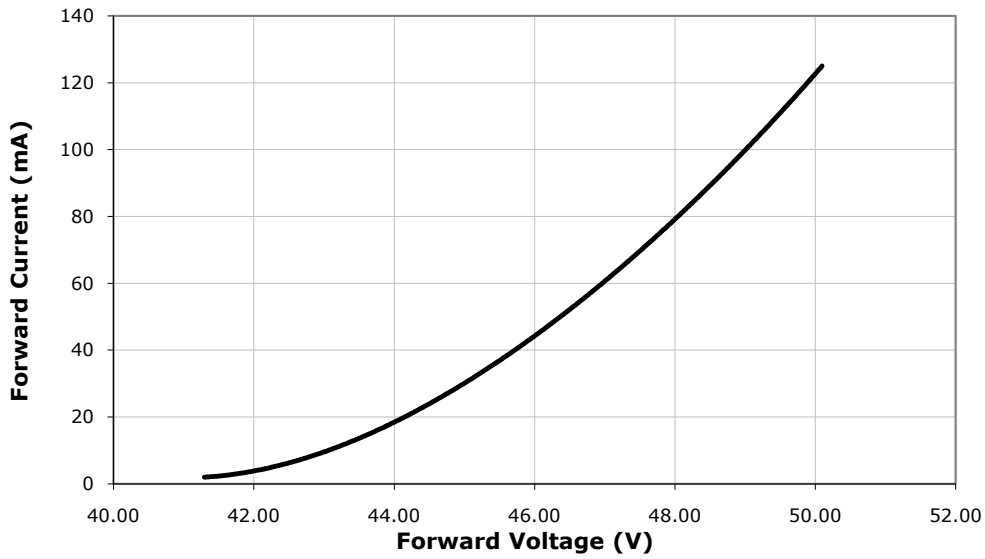
**RELATIVE SPECTRAL POWER DISTRIBUTION**



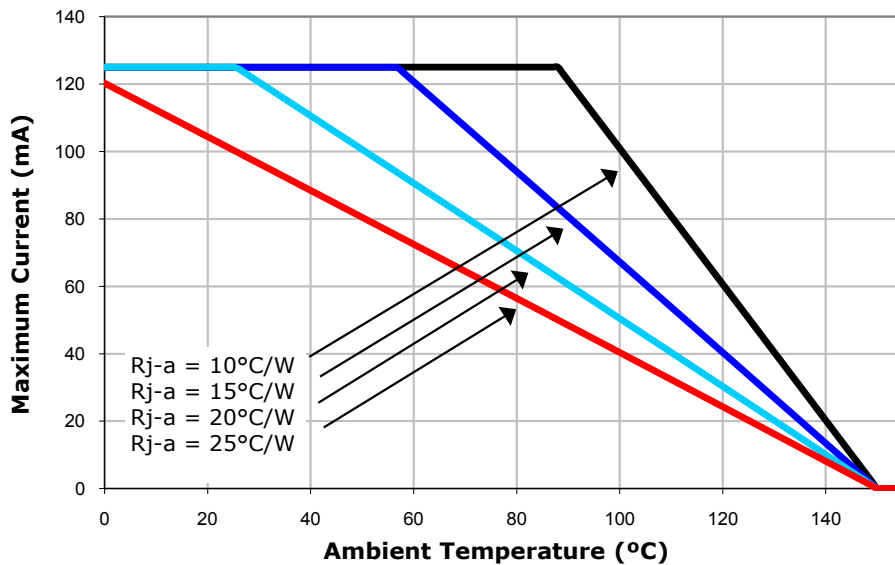
**RELATIVE FLUX VS. JUNCTION TEMPERATURE ( $I_f = 44$  MA)**



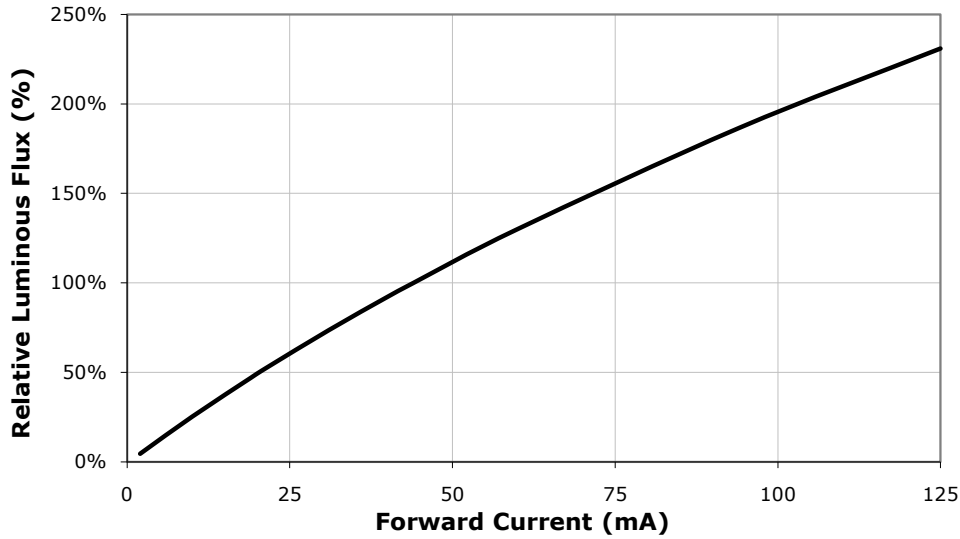
**ELECTRICAL CHARACTERISTICS ( $T_j = 85\text{ }^\circ\text{C}$ )**



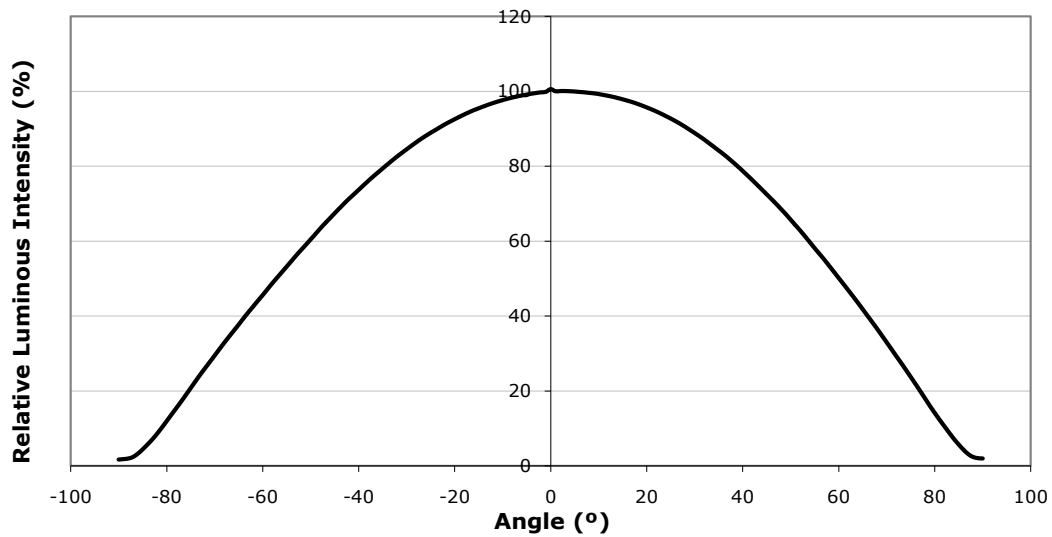
**THERMAL DESIGN**



**RELATIVE FLUX VS. CURRENT ( $T_j = 85\text{ }^\circ\text{C}$ )**



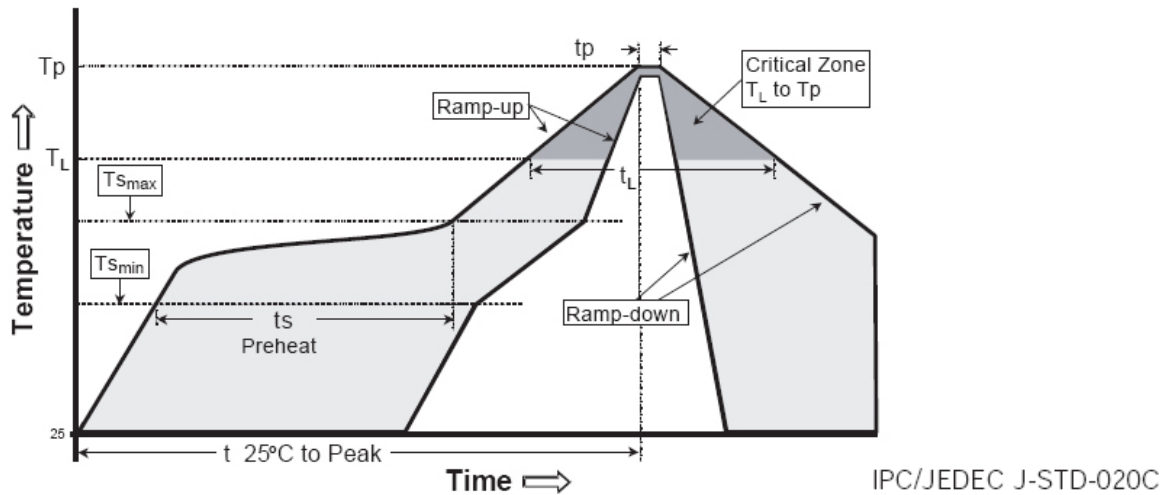
**TYPICAL SPATIAL DISTRIBUTION**



## REFLOW SOLDERING CHARACTERISTICS

In testing, Cree has found XLamp XM-L LEDs to be compatible with JEDEC J-STD-020C, using the parameters listed below. As a general guideline, Cree recommends that users follow the recommended soldering profile provided by the manufacturer of the solder paste used.

Note that this general guideline may not apply to all PCB designs and configurations of reflow-soldering equipment.

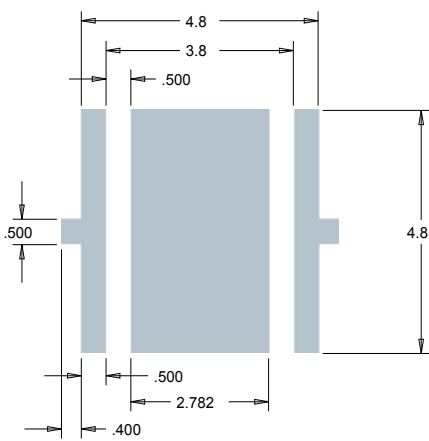
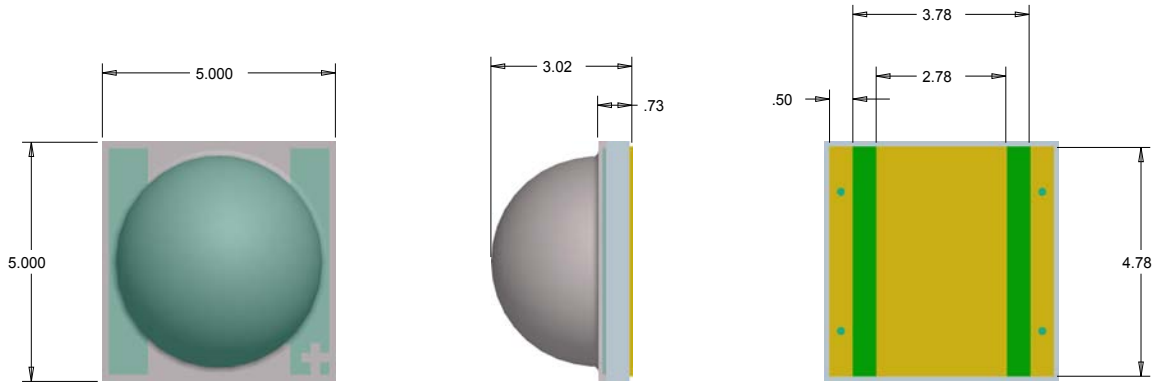


Profile feature	Lead-based solder	Lead-free solder
Average ramp-up rate ( $T_{S_{MAX}}$ to $T_p$ )	3 °C/second max	3 °C/second max
Preheat: Temperature min ( $T_{S_{MIN}}$ )	100 °C	150 °C
Preheat: Temperature max ( $T_{S_{MAX}}$ )	150 °C	200 °C
Preheat: Time ( $t_{S_{MIN}}$ to $t_{S_{MAX}}$ )	60-120 seconds	60-180 seconds
Time maintained above: temperature ( $T_L$ )	183 °C	217 °C
Time maintained above: time ( $t_L$ )	60-150 seconds	60-150 seconds
Peak/classification temperature ( $T_p$ )	215 °C	260 °C
Time within 5 °C of actual peak temperature ( $t_p$ )	10-30 seconds	20-40 seconds
Ramp-down rate	6 °C/second max	6 °C/second max
Time 25 °C to peak temperature	6 minutes max	8 minutes max

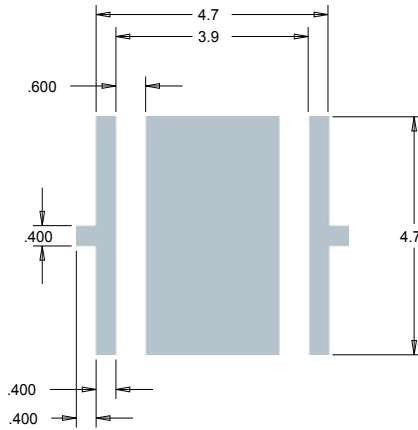
Note: All temperatures refer to topside of the package, measured on the package body surface.

**MECHANICAL DIMENSIONS**

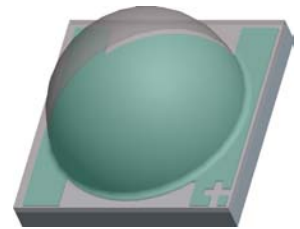
All measurements are  $\pm .13$  mm unless otherwise indicated.



RECOMMENDED PCB SOLDER PAD



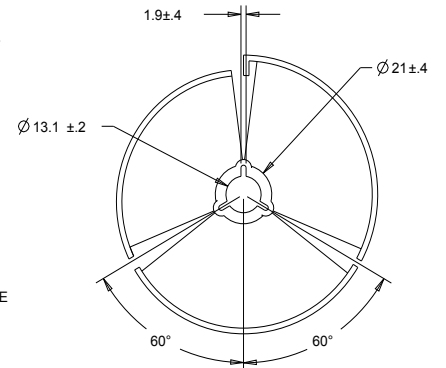
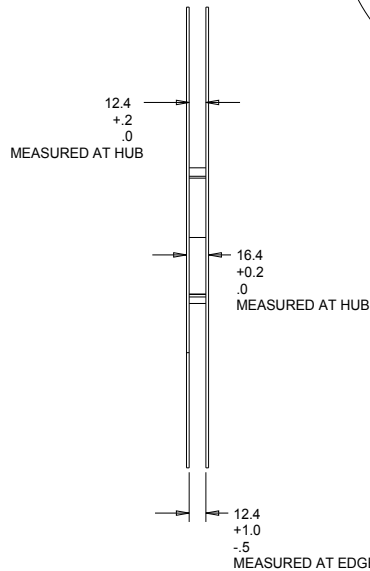
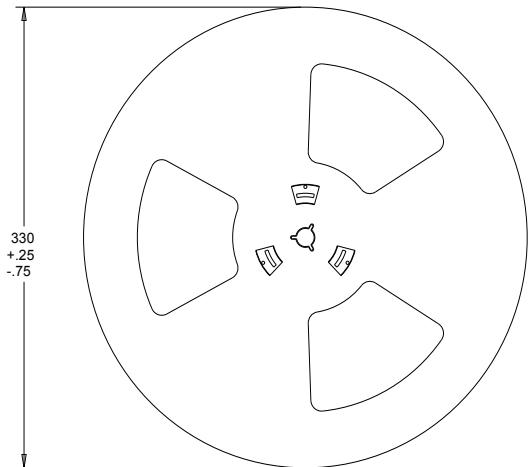
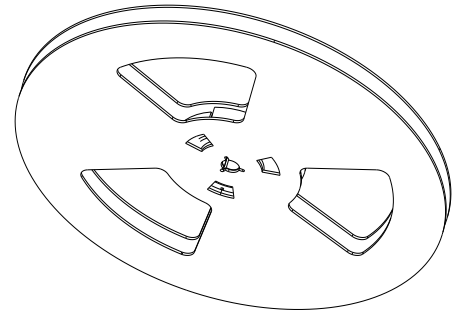
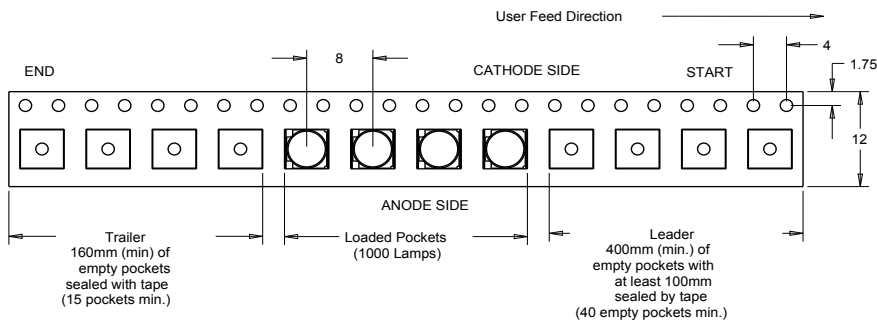
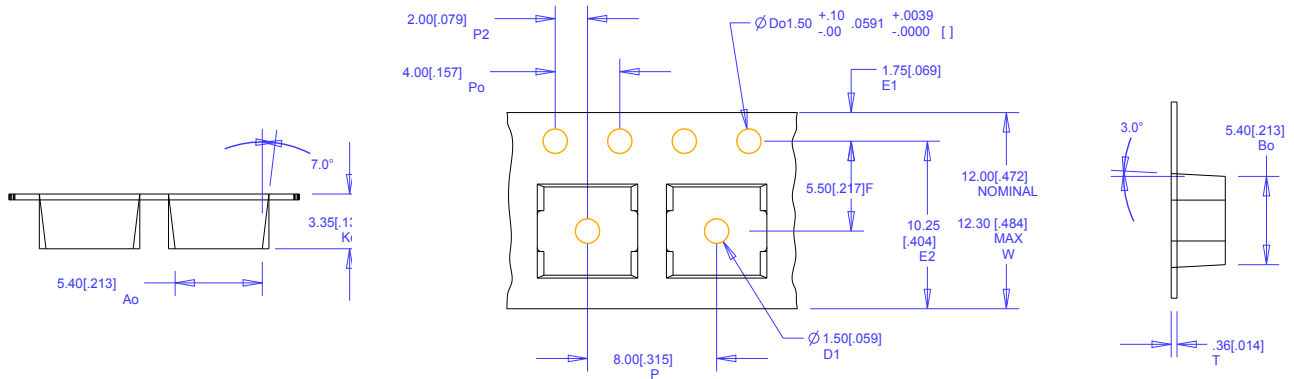
RECOMMENDED STENCIL PATTERN  
SHADED AREA IS OPEN



**TAPE AND REEL**

All Cree carrier tapes conform to EIA-481D, Automated Component Handling Systems Standard.

All dimensions in mm.





**PACKAGING**

